

Press-fit tails

(1.27 mm) .050"

SEAMP, SEAMI SERIES

HIGH-SPEED/HIGH-DENSITY OPEN-PIN-FIELD

Mates with:
SEAF, SEAF-RA-GP

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAMP

Insulator Material: Natural LCP
Contact Material: Copper Alloy
Operating Temp Range: -55 °C to +125 °C
Current Rating: 2.5 A per pin (6 adjacent pins powered)
Plating: Au or Sn over 50 μ" (1.27 μm) Ni
Contact Resistance: 8.7 mΩ
Working Voltage: 215 VAC
RoHS Compliant: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Note: Compliant pin fixture CAT-SEAMP-XX-XX. Patent Pending.

SEAMP

NO. OF POSITIONS PER ROW

02.0

PLATING OPTION

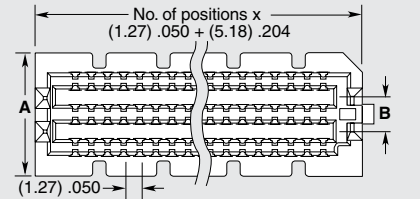
NO. OF ROWS

OPTION

SEAMP
= Press-fit

-10, -20, -30, -40, -50

NO. OF ROWS	A	B
-04	(7.06) .278	(2.54) .100
-06	(9.60) .378	(2.54) .100
-08	(12.14) .478	(5.08) .200
-10	(14.68) .578	(7.62) .300



-L
= 10 μ" (0.25 μm)
Gold on contact area, Matte Tin on tail

-S
= 30 μ" (0.76 μm)
Gold on contact area, Matte Tin on tail

-04
= Four Rows

-06
= Six Rows

-08
= Eight Rows

-10
= Ten Rows

-GP
= Guide Post (Mates with SEAF-RA-GP only)

-TR
= Tape & Reel

HIGH-SPEED CHANNEL PERFORMANCE

SEAMP/SEAF @ 7 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

32
Gbps

Processing: Application tooling and one ton minimum press required. Contact ATG@samtec.com for more information.

Mates with:
SEAF

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAMI

Insulator Material: Black LCP
Contact Material: Copper Alloy
Operating Temp Range: Testing Now!
Plating: Au or Sn over 50 μ" (1.27 μm) Ni
Contact Resistance: Testing Now!
Working Voltage: Testing Now!
RoHS Compliant: Yes
Lead-Free Solderable: Yes

ALSO AVAILABLE (MOQ Required)

- Other plating options
 - 20 & 30 pins per row
 - 04 & 06 rows
- Contact Samtec.

Note: Patented

Note: Some sizes, styles and options are non-standard, non-returnable.

SEAMI

NO. PINS PER ROW

11.0

PLATING OPTION

NO. OF ROWS

SOLDER TYPE

A

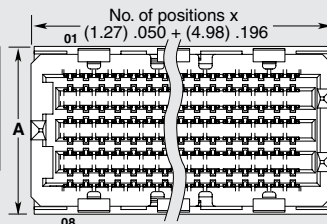
K

TR

SEAMI
= 85 Ω tuned

-40, -50

NO. OF ROWS	A	B
-08	(13.41) .528	(5.08) .200
-10	(15.95) .628	(7.62) .300



-L
= 10 μ" (0.25 μm)
Gold on contact area, Matte Tin on solder tail

-S
= 30 μ" (0.76 μm)
Gold on contact area, Matte Tin on solder tail

-08
= Eight Rows

-10
= Ten Rows

-1
= Tin/Lead Alloy Solder Charge

-2
= Lead-Free Solder Charge

-A
= Alignment Pins

-K
= Polyimide film Pick & Place Pad

-TR
= Tape & Reel

MATED HEIGHTS*

SEAMI LEAD STYLE	SEAF LEAD STYLE	-05.0	-06.0	-06.5
-11.0	16 mm	17 mm	17.5 mm	

*Processing conditions will affect mated height.

HIGH-SPEED CHANNEL PERFORMANCE

SEAMI/SEAF @ 16 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

17
Gbps